

## HPI

TE Internal #: 1-2390136-5 HPI, PCB Mount Header, Wire-to-Board, 15 Position, .049 in [1.25 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Power & Signal, Natural

### View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 15

Number of Rows: 1

Centerline (Pitch): 1.25 mm [.049 in ]

Termination Method to Printed Circuit Board: Surface Mount

## Features



## Product Type Features

Connector System	Wire-to-Board	
Header Type	Fully Shrouded	
Sealable	No	
Connector & Contact Terminates To	Printed Circuit Board	
PCB Connector Assembly Type	PCB Mount Header	
Configuration Features		
Number of Positions	15	
Number of Rows	1	
Electrical Characteristics		
Termination Resistance	20 mΩ	
Insulation Resistance	100 MΩ	
Dielectric Withstanding Voltage (Max)	500 V	
Body Features		
Primary Product Color	Natural	

**C** For support call+1 800 522 6752

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## **Contact Features**

Contact Layout	Staggered	
PCB Contact Termination Area Plating Material Thickness	2 µm[80 µin]	
Contact Underplating Material Thickness	1.27 – 2.7 μm[50 – 106 μin]	
Contact Mating Area Plating Material Thickness	2 µm[80 µin]	
PCB Contact Termination Area Plating Material Finish	Matte	
Contact Mating Area Plating Material Finish	Matte	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	Tin	
Contact Base Material	Brass	
Contact Mating Area Plating Material	Tin	
Contact Type	Pin	
Contact Current Rating (Max)	1 A	
Termination Features		
Termination Method to Printed Circuit Board	Surface Mount	
Mechanical Attachment		
Mating Alignment Type	Polarization	
Mating Retention	With	
PCB Mount Retention Type	Solder Peg	
Mating Retention Type	Latch	
Connector Mounting Type	Board Mount	
Mating Alignment	With	
PCB Mount Alignment	Without	
PCB Mount Retention	With	
Housing Features		
Mating Entry Location	Side	
Housing Material	LCP	
Centerline (Pitch)	1.25 mm[.049 in]	
Usage Conditions		
Operating Temperature Range	-40 - 105 °C[-40 - 221 °F]	
Operation/Application		
Assembly Process Feature	Pick and Place Cover	
	03/21/2022 09.1	

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Circuit Application	Power & Signal
ndustry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	1500
Packaging Type	Carton, Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Compliant with Exemptions
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Not Yet Reviewed
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	

### Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Not reviewed for solder process capability

### Solder Process Capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

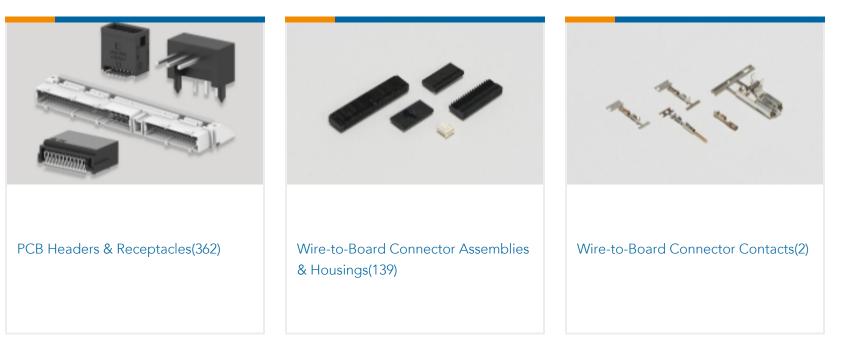
# **Compatible Parts**

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# Also in the Series | HPI



# Customers Also Bought



TE Part #2-1623795-3 SQP2 R047 5% WIRE	TE Part #1-1630019-4 HSC200 2K4 5%	TE Part #9-2176397-4 3502 7K5 1%	TE Part #1-1969694-4 PTL 1X4 PCB HEADER R/A HITEMP KEY A LGR
TE Part #YDTS24T15-18PNV001 RECP ASSY	TE Part #YDTS24T21-35SNV001 RECP ASSY	TE Part #YACT24ME35PNV00100 JAM NUT RECEPTACLE	TE Part #YD369-B99-AP400000 369 9 WAY PANEL MNT REC, 90 PCB GOLD,PIN



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# Documents

Product Drawings 1.25P 15POS WTB R/A BRD W LATCH TIN NA

English

## **CAD** Files

3D PDF

3D

Customer View Model ENG\_CVM\_CVM\_1-2390136-5\_1.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-2390136-5\_1.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-2390136-5\_1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

## **Product Specifications**

English